

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently Amended) Method for selectively transferring components from a donor substrate to a target substrate, said donor substrate comprising an assembly of components, the method comprising the following steps:
 - a) gluing of the assembly of components from the donor substrate onto a handle substrate by the intermediary of a glue layer,
 - b) thinning of the donor substrate to provide a layer comprising the assembly of components,
 - c) degradation of the adherence of the glue layer gluing a sub-assembly of components to be transferred,
 - d) displacement of the sub-assembly of components to be transferred onto the target substrate, the sub-assembly of components to be transferred being bonded onto the target substrate by direct molecular gluing, said displacement occurring after the step of degradation of the adherence of the glue layer;
 - e) separation of the sub-assembly of components to be transferred and the handle substrate;repeating steps c), d) and e) to transfer other subassemblies of components.
2. (Original) Method according to claim 1, wherein a glue used is chosen from among an epoxy glue, a glue to be hardened by ultraviolet radiation, a polymer base glue, or a glue with a wax base.
3. (Previously Presented) Method according to claim 1, wherein degradation of the glue layer is carried out by submitting it to a chemical treatment, a heat treatment, a radiation treatment or a plasma treatment or a combination of said treatments.
- 4-5. (Canceled)

6. (Previously Presented) Method according to claim 1, wherein the handle substrate comprises access paths towards a face of the handle substrate able to be put into contact with the layer of glue.

7. (Canceled)

8. (Previously Presented) Method according to claim 1, wherein the separation step includes applying traction, pressure, shearing, peeling or bending forces, or any combination of these forces.

9. (Previously Presented) Method according to claim 8, wherein the separation step further includes applying a jet of fluid.

10. (Previously Presented) Method according to claim 8, wherein the separation step further includes the insertion of a tapered object.

11. (Currently Amended) Method according to claim 14 ~~wherein said step of degradation of the adherence of the glue layer is carried out before said step of displacement of~~ further comprising displacing the components to be transferred onto the target substrate after said degrading is performed.

12. (Previously Presented) Method according to claim 1 wherein said step of degradation of the adherence of the glue layer causes a modification of a mechanical hold compatible with ulterior separation.

13. (Previously Presented) Method according to claim 1, comprising a step of cutting out the layer comprising the assembly of components by making grooves to individualize the components.

14. (Currently Amended) Method for selectively transferring components from a donor substrate to a target substrate, the method comprising:

gluing of an assembly of components on the donor substrate onto a handle substrate with a glue layer;

thinning the donor substrate to provide a layer comprising the assembly of components;

degrading an adherence of the glue layer between a sub-assembly of components on the layer and the handle substrate;

coupling the sub-assembly of components by direct molecular bonding onto a target substrate after degrading the adherence of the glue layer; and

separating the sub-assembly of components from the handle substrate, wherein the sub-assembly of components are disposed on the target substrate.

15. (New) Method according to claim 1 further comprising applying heat treatment to the transferred sub-assembly of components bonded to the target substrate to reinforce the direct molecular gluing.

16. (New) Method according to claim 14 further comprising applying heat treatment to the sub-assembly of components coupled to the target substrate to reinforce the direct molecular bonding.